

RUBBER AND/OR PLASTIC MOLDED ARTICLE HAVING INSULATING PROPERTY, VIBRATION DAMPING PROPERTY AND HEAT CONDUCTIVITY

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Abstract of JP7145270

PURPOSE: To obtain a rubber and/or plastic molded article having prescribed physical properties and excellent sound-insulation effect and heat-dissipation and useful as an insulating sealant for LSI, etc., by compounding a polymer such as rubber with a hydroxyl-containing organic compound and a filler such as a metal oxide and molding the composition.

CONSTITUTION: The objective molded article 1 having an electrical insulation performance represented by the volume resistivity of $\geq 1 \times 10^9 \Omega \text{cm}$, a vibration damping performance represented by the loss coefficient of 0.25-0.95 and a heat-conducting performance represented by a thermal conductivity of $\geq 0.4 \text{ kcal/m.h. deg.C}$ is produced by molding a composition obtained by compounding (A) a polymer 2 composed mainly of a rubber such as natural rubber and/or a plastic such as PE with (B) an organic compound 3 having hydroxyl group such as glycerol and (C) fillers consisting of (i) one or more kinds of fillers 4 selected from metal oxides such as aluminum oxide, metal nitrides such as boron nitride and fillers containing either one of the above metallic compounds and/or (ii) one or more kinds of fillers 4 selected from crystalline silica, silicon carbide, silicon oxide and fillers containing either one of the above compounds.

